



Information for Sponsors

(plus exhibition)



2005 IST SUMMIT
19-23 June 2005
Dresden - Germany
www.mobilesummit2005.org

Chairman: Gerhard Fettweis
Vodafone Chair, TU Dresden



IST Summit at a Glance

The European event on wireless communications

- All European R&D projects will be present at this forum of the 6th framework programme
- The summit brings together experts from the worldwide wireless industry and research communities
- The summit increasingly focuses on a high-quality technical programme and plenary sessions
- Recent advances in all fields related to mobile and wireless communications will be presented, including key technologies, standardization, demonstrations, conference talks, panel discussions.

Programme

- Sun, June 19, 2005: **tutorials** and a **welcome reception**
- Mon-Wed, June 20-22: three full conference days
- The technical programme will be complemented by a series of workshops, to be held on June 23, 2005
- The **conference dinner** will take place in downtown Dresden on Tue, June 21. It is included in a full registration
- To say "Thank you" to our commercial and institutional sponsors, TPC members, and keynote speakers, we would like to invite you to a special **banquet** in one of Dresden's prominent castles on Mon, June 20
- Activities around the summit include cultural highlights (e.g. Semper Opera), and physical exercises (e.g. hiking in Saxon Switzerland)

Expected participation

- 2004: 13th IST summit in Lyon, France: 560 attendees
- 2005: 14th IST summit in Dresden:
 - We expect more than 550 attendees, mainly from Europe
 - North American and Asian participants account for between 20 and 30 % of attendance
 - At least three parallel sessions for three full days
 - Approx. 150 papers presentations, approx. 70 posters
- **As of Feb 6, we have received a total of 501 submissions – compared to 271 in 2004.**

History

- Since 1996 (previously as ACTS + RACE summits)
- 1996 Granada, Spain; 1997 Aalborg, Denmark; 1998 Rhodes, Greece; 1999 Sorrento, Italy; 2000 Galway, Ireland; 2001 Barcelona, Spain; 2002 Thessaloniki, Greece; 2003 Aveiro, Portugal; 2004 Lyon, France
- **2005 Dresden, Germany**
- 2006 Athens, Greece; 2007 Budapest, Hungary



Dresden - Location

Dresden

- Halfway between Berlin and Prague
- 510,000+ people
- Airport with frequent connections to major European hubs





No.1 semiconductor site in Europe, No.5 on the planet

- 25000 to 30000 employees total with new AMD fab

Major semiconductor players

- Wacker 6" & 12" wafer production
- Dupont Photomasks
- Infineon (2x 8" DRAM & logic fabs / 1x 12" DRAM fab)
- AMD (2x 8" processor fab / 1x 12" processor fab under construction)
- ZMD, mixed signal ASIC design, and 6" fab
- Philips Semiconductors (Systemonic)
- Applied Materials Europe headquarters (moved from Munich)
- ATMEL design center

Major wireless players

- GSM/GPRS/UMTS/3G: VodafoneD2 East, Radioplan
- WLAN 802.11: AMD, Philips Semiconductors, ATMEL
- ZigBee: ZMD, ATMEL
- RFID / NFC: ZMD, KSW, Digades
- DVB-T/S/C: TechniSat, Philips Semiconductors
- GPS: ATMEL

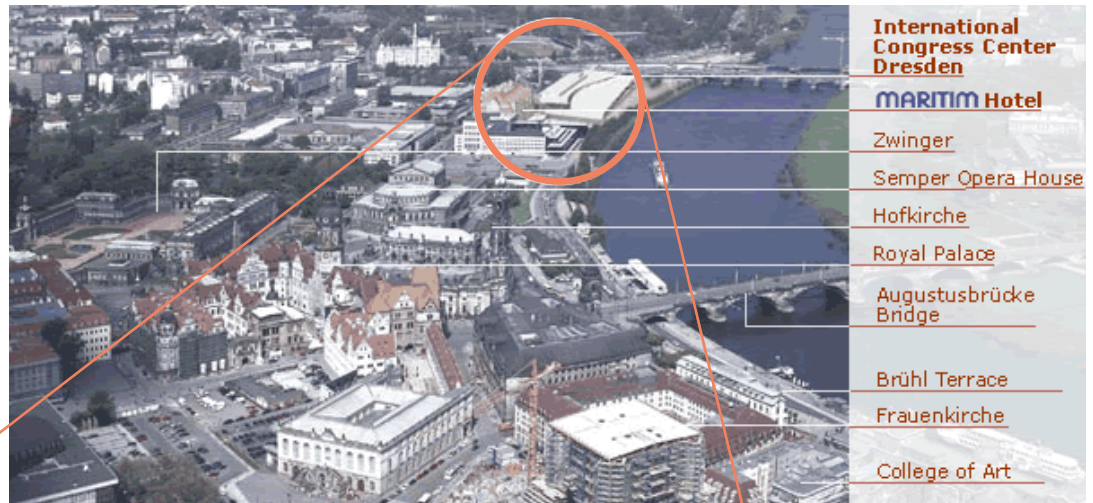
Major R&D

- TU Dresden with 30460 students
- Fraunhofer with 8 institutes and 1000 employees
- Max Planck with 3 institutes and 600 employees
- Leibnitz Gesellschaft with 4 institutes and 1500 employees

Networks

- Silicon Saxony with 150 members and growing!

International Congress Center Dresden (ICCD)



- The International Congress Center of Dresden rises in the heart of the historical city amongst its popular sights: the Semper Opera House, the Zwinger or the Frauenkirche.
- The congress center offers a variety of conference rooms and facilities with variable capacity, allowing for a flexible and convenient arrangement of the venue.
- A number of excellent transportation connections exist for anyone wishing to arrive in Dresden by motorway, railway or the airport.
- The ICCD opened in May 2004.



Partners of IST Summit 2005

Commercial Partners



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Institutional Partners





Why to Sponsor

As a sponsor, you have the opportunity to gain an immense publicity:

- The IST summit heads towards becoming a global, world-class event – based on Europe's excellence in R&D, standardization and development of applications and services.
- The IST summit already is Europe's premier event in mobile communications, bringing together industry leaders and scientists from around the globe to debate, discuss and learn about the technologies, business opportunities and new applications.
- All European R&D projects of the current sixth framework programme and their leaders will be present.
- Sponsors enjoy extraordinary visibility with the powerful audience at the conference, because they have their undivided attention. There is no competition for time between conference sessions and networking receptions. The character of the event as a place where important ideas are exchanged is evident and continually reinforced throughout the event.
- The IST summit attracts an audience that is a "Who's Who" in mobile, wireless R&D – including leading customers, operators, vendors, researchers, investors and press. Attendees mingle with colleagues in a relaxed, casual environment, and discuss the future of mobile communication with the very people who are shaping that future.
- IST summit sponsors gain access to research executives and directors of some of the world's leading R&D organizations and project representatives of FP6 projects. The event's attendees are responsible for setting R&D and product development goals and have a considerable budget responsibility.
- Sponsors enjoy an invitation to the special "VIP" dinner. Sponsors, TPC members, and invited speakers will gather in one of Dresden's castles for a unique discussion and networking event.
- The IST summit has a long track record and an increasingly powerful, loyal audience. Now in its 14th year, the IST summit enjoys a reputation as "major mobile communication event".



How to Sponsor

In short, sponsoring the IST summit represents a possibility to

- establish both relationships and partnerships,
- enhance your organization's reputation and profile,
- contact potential customers and employees.

Benefits go beyond just spreading the brand name.

Steps towards sponsoring

- Sponsorship packages
 - We offer turnkey sponsorship packages that are described on the next pages.
 - Choosing a package just requires filling in the corresponding data in the attached sponsoring agreement (Annex I remains as is in this case), and sending two signed copies to

Prof. Dr.-Ing. Gerhard Fettweis
Technische Universität Dresden
Vodafone Chair Mobile Communications Systems

D-01062 Dresden

- Tailoring sponsorship solutions
 - In addition to the sponsorship packages, we are open for ideas and negotiations that allow for tailoring the sponsorship to your needs.
 - In this case, we will adapt annex I of the sponsoring agreement accordingly.



Sponsoring Packages

1. Platinum sponsorship – the premium package

- This premium sponsor package provides the highest profile and exposure to wireless professionals from industry, government, and academia.
- Major benefits:
 - Key note speech
 - Complimentary large exhibition booth
 - Opportunity for a three-minute address at the conference dinner
 - Two insertions of suitable literature in the conference bag (supplied by sponsor)
 - Participation in the press conference
 - Full page advertisement for your company (supplied by sponsor) in the conference programme
 - Prominent recognition of your organization's brand on all conference material, including programme, web page, banners, conference proceedings, displays in conference rooms, and any promotional material printed after your subscription
 - Acknowledgment as a major sponsor by the Chairman at the welcome reception, the opening ceremony, and the conference dinner
 - Exterior flags in front of the ICCD (supplied by sponsor)
 - Five complimentary full-registrations
 - Three invitations to the exclusive "VIP" dinner
- From € 40,000 excl. VAT (16%)



Sponsoring Packages

2. Gold sponsorship

- Major benefits:
 - Key note speech
 - Complimentary medium exhibition booth
 - Two insertions of suitable literature in the conference bag (supplied by the sponsor)
 - Full page advertisement for your company (supplied by the sponsor) in the conference programme
 - Suitable recognition of your organization's brand on all conference material, including programme, web page, conference proceedings, displays in conference rooms, and any promotional material printed after your subscription
 - Acknowledgement as a major sponsor
 - Three complimentary full-registrations
 - Two invitations to the exclusive "VIP" dinner
- From € 20,000 excl. VAT (16%)

3. Silver sponsorship

- Major benefits:
 - Complimentary small exhibition booth
 - One insertion of suitable literature in the conference bag (supplied by the sponsor)
 - Half page advertisement for your company (supplied by the sponsor) in the conference programme
 - Recognition of your organization's brand on all conference material, including programme, web page, conference proceedings, displays in conference rooms, and any promotional material printed after your subscription
 - Acknowledgement as a major sponsor
 - Two complimentary full-registrations
 - One invitation to the exclusive "VIP" dinner
- From € 10,000 excl. VAT (16%)



Individual Sponsoring Items

All prices are indicative and subject to negotiations, and do not include VAT (16%).

Full page advertisement in the programme (inside front or back)

- Full page advertisement € 1,500
- Half page advertisement € 750

Advertising in conference case

- Insertion of one A4 piece of literature (supplied by sponsor) into the conference case
- € 1,500

Conference pads

- Insertion of an A4 pad (supplied by sponsor) into each conference case, displaying your company name and logo.
- Only one available
- € 1,500

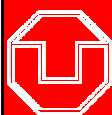
Conference pens

- Insertion of a pen (supplied by sponsor) into each conference case, displaying your company name and logo. Other items for inclusion in the case available on request.
- Only one available
- € 500

Other items

(upon request, negotiated directly with the organizer)

- **Exhibition stand:** dressed directly by the sponsor according to it's requirements and wishes
- **Displays:**
 - Logos on a large PVC banner
 - Large drop paper banners, hung in the entrance hall



Packages at a Glance

	Platinum	Gold	Silver
PRICE (in €, excl. VAT)	> 40.000	> 20.000	> 10.000
Key note speech	10 min	5 min	
Exhibition booth	large	medium	small
Opportunity to address delegates at	dinner		
Insertions of suitable literature in the conference bag	2	2	1
Press conference participation	x		
Advertisement in the conference programme	1 page	1 page	½ page
Prominent recognition of logos on all material	x	x	x
Acknowledgment as a major sponsor	x	x	x
Flags in front of the ICCD	x		
Complementary full registrations	5	3	2
Invitations to "VIP" dinner	3	2	1



Why to Exhibit

A broad exhibition combining stands presenting

- projects supported and funded by the European commission, and
- stands presenting institutional entities and commercial or industrial companies

will be held simultaneously with and close to the sessions.

Exhibitors at the summit are offered a singular opportunity to communicate with all summit participants over the entire duration of the conference.

To enhance this communication, time will be set aside to allow participants to visit the exhibition, notably during breaks or sessions.

The exhibition will be held in an **area between the conference rooms and the restaurant**, with **coffee and refreshments served directly among the stands**.

Access for all participants is therefore convenient and “natural”, thereby enabling frequent visits and discussions with exhibitors.

Reservation of an exhibition space entitles you to register one person free of charge; this registration includes free access to conferences, lunches and breaks.



Exhibitor Pack

The cost of a stand includes a set of services:

- The stand includes signs, lighting, chairs, power supply and a table as well as assistance for installation
- You can dress your stand according to your own requirements
- Your inclusion in the exhibitor catalogue
 - The catalogue is part of the official programme and placed in the bag given to each participant.
 - It describes all exhibitors, with one double-sided page presenting your company
- Continuous free access to the bar
- One full conference registration
- A copy of conference proceedings (CD)
- You will be mentioned in the CD in the exhibitor section with a direct internet link to your site
- As of registration as an exhibitor, you will be mentioned on the WEB site publicising this conference (this site is currently highly visited)
- Security guarding by accredited personnel
- Cleaning service

Timing

- Installation: possible from Sun, June 19, 2005
- Exhibition: Mon June 20 – Wed June 22, 2005

Costs

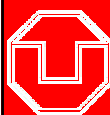
- Basic module (9m²) €2,000
- Additional module (9m²) €1,000

Please use our reservation request form (last page) for booking a booth at the exhibition.



Additional Information

- Call for papers
- Expected participation by region
- Draft programme of the summit
- Technical Programme Committee, Organizers, Contact information



Call for Papers

14th IST Mobile and Wireless Communications Summit

Placing people at the centre of an 'all-communicating' world is the exciting vision of ambient intelligence. New paradigms in the areas of network design, transmission technology, hardware and software solutions, applications, services, and business models will be necessary to realize such interactive environments. The arising challenges are currently being addressed in a number of research projects within the European Information Society Technologies (IST) framework.



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radio**plan**
SIGNALION



2005 IST SUMMIT 19-23 June 2005 Dresden - Germany www.mobilesummit2005.org

Chairman

G. Fettweis, TU Dresden

Technical Programme Committee

H. Abramowicz, H. Aghvami, H. Bauer,
S. Benedetto, F. Berens, E. Biglieri, J. Bitó,
N. Blefari-Melazzi, H. Boche, D. Bourse,
V. Brankovic, F. Casadevall Palacio, B. Casali,
K. Chen, Z. Chen, P. Chevillat, N. Chuberre,
V. Conan, L. Correia, E. D'Andrea, K. David,
M. Dillinger, M. Dinis, C. Dosch, C. Douillard,
E. Edvardsen, H. Eikerling, H. Einsiedler,
K. El-Khazen, A. Finger, I. Frigyes, A. Gameiro,
A. Goldsmith, D. Grace, J. Hagenauer,
L. Hérault, W. Hirt, A. Jahn, N. Jefferies,
P. Jung, S. Kaiser, G. Karetsos, M. Klemettinen,
R. Kohno, S. Kyriazakos, C. Lamy, R. Lehnert,
K. Letaief, J. López Caravantes, P. Mähönen,
T. Meng, H. Meyr, A. Mihovska, I. Moerman,
W. Mohr, I. Oppermann, E. Pallis, S. Park,
R. Paschetto, M. Pätzold, S. Ponnkant,
R. Prasad, E. Protonotarios, C. Schäffer,
H. Schotten, C. Selier, R. Tafazolli,
S. Theodoridis, T. Tjelta, R. Urbanke,
M. Uusitalo, I. Verbauwhede, J. Vidal, B. Walke,
M. Werner, F. Williams, A. Wolisz

Local Organization

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The 14th IST Summit focuses on bringing together experts from the worldwide wireless industry and research communities, with a special emphasis on providing a forum for European research initiatives. Recent advances in all fields related to mobile and wireless communications will be presented, thereby facilitating the identification of future trends, illumination of business opportunities, and discussion on the future roles of various bodies from academia, industry, and research centres in helping to form the vision of an ambient, truly intelligent communications environment.

Authors are invited to submit high-quality papers representing original results in all areas of wireless communications systems and networks, including their terrestrial, satellite and high altitude platform components. Submitted papers should not exceed five pages.

Authors of selected best papers will be invited to submit an extended version of their papers for publication in a special issue of European Transactions on Telecommunications.

Important dates

Submission deadline:	31 January 2005
Notification of acceptance:	15 March 2005
Final paper due:	15 April 2005
IST Summit 2005:	19-23 June 2005



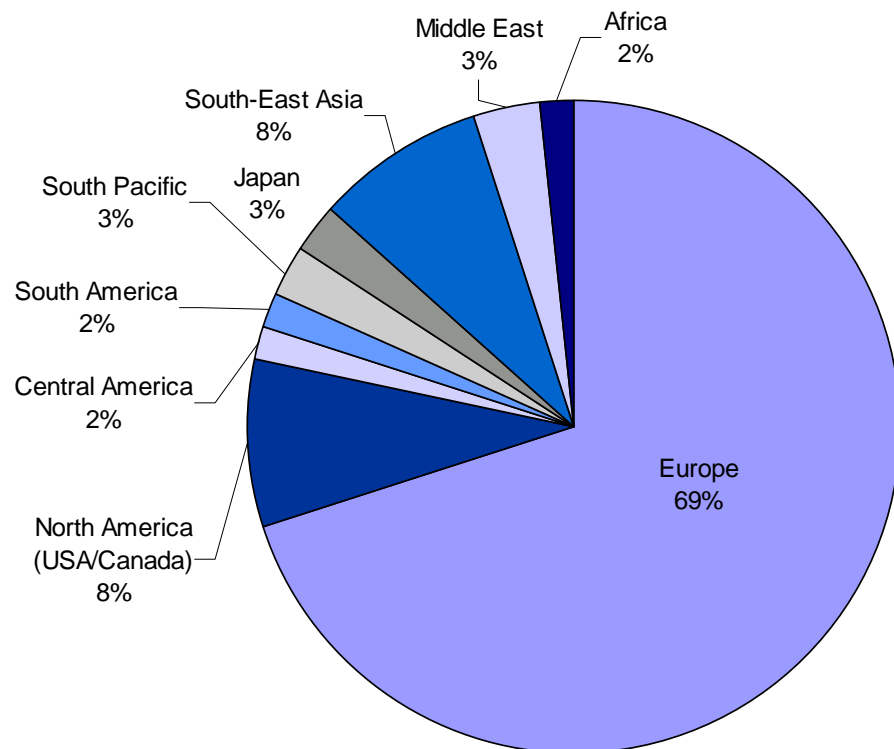


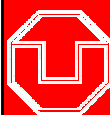
Expected Participation

Number of expected participants by region

- Based on data from past IST summits

Europe	420
of which from Northern Europe	50
of which from Southern Europe	100
of which from Eastern Europe	50
of which from Western Europe	120
of which from Germany	100
North America (USA/Canada)	50
Central America	10
South America	10
South Pacific	15
Japan	15
South-East Asia	50
Middle East	20
Africa	10
Total expected participation	600



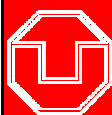


Day 1: Sun, 19 June 2005

Time	Track 1	Track 2	Track 3	Track 4	Track 5
13:00	Tutorial T1: Digital Multimedia Broadcasting	Tutorial T2: OFDM and MC-CDMA for Future Broadband Wireless Communications	Tutorial T3: End-to-End Reconfigurability	Tutorial T4: Disciplined Design of System-on-Chip	Sight-Seeing Tour*
16:30					
19:30 - 22:00	Welcome Reception Porcelain Collection, Dresden Zwinger				

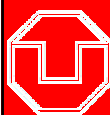
Day 2: Mon, 20 June 2005

Time	Track 1	Track 2	Track 3	Track 4	Track 5	Track 6
09:00	Opening Ceremony Großer Saal					Exhibition
09:20	Panel B3G and 4G: What is it good for? Großer Saal					
10:30	Coffee break					
11:00	Satellite Systems I Saal 1	Coding & Modulation Saal 2	Hardware I: Implementation Konferenz 1	Cellular Systems I: Capacity & HSxPA Konferenz 2	Poster Ad Hoc Networks Poster area	
12:30	Lunch break					
14:00	Satellite Systems II Saal 1	Source & Channel Coding Saal 2	Hardware II: Antennas & RF Konferenz 1	Cellular Systems II: CDMA Konferenz 2	Poster QoS & Scheduling Poster area	
15:30	Coffee break					
16:00	Applications & Business Models Saal 1	Channel Estimation & Positioning Saal 2	Trials & System Evaluation Konferenz 1	Broadcast Systems & Convergence Konferenz 2	Poster Hardware: Implementation & Reconfigurability Poster area	
17:30						
19:00 - 22:45	Wine Tour*					



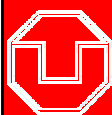
Day 3: Tue, 21 June 2005

Time	Track 1	Track 2	Track 3	Track 4	Track 5	Track 6
09:00	Special session 4G System Proposals in Asia Großer Saal	Equalization & Interference Cancellation Saal 2	Hardware III: Dirty RF Konferenz 1	Cross-Layer Optimization Konferenz 2	Poster PHY I Poster area	Exhibition
10:30	Coffee break					
11:00	Novel Networks & Relaying Saal 1	OFDM & MC-CDMA Systems Saal 2	Security Konferenz 1	QoS & Scheduling I Konferenz 2	Poster Broadcast, Satellite & HAPS Systems Poster area	
12:30	Lunch break					
14:00	Ad Hoc Networks Saal 1	MIMO-OFDM Saal 2	Service Access & Mobility Konferenz 1	QoS & Scheduling II Konferenz 2	Poster UWB Systems Poster area	
15:30	Coffee break					
16:00	Panel The Trend Towards Simplicity Großer Saal					
17:30						
20:00 - 23:00	Gala Dinner Taschenbergpalais - Hotel Kempinski					



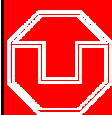
Day 4: Wed, 22 June 2005

Time	Track 1	Track 2	Track 3	Track 4	Track 5	Track 6
09:00	Special session WWRF Großer Saal	MIMO: Transmission Algorithms Saal 2	Hardware IV: Reconfigurability Konferenz 1	Network Architecture & Reconfigurability Konferenz 2	Poster PHY II Poster area	Exhibition
10:30	Coffee break					
11:00	UWB I Saal 1	Advanced Receivers for MIMO & MUD Saal 2	Multiple Access & OFDMA Konferenz 1	RRM & Dynamic Spectrum Management Konferenz 2	Poster Networks: Architectures & Reconfigurability Poster area	
12:30	Lunch break					
14:00	UWB II: Coexistence & Interference Saal 1	Propagation & Channel Measurements Saal 2	Multi-Radio Access Konferenz 1	Broadband, Fixed Wireless Access & HAPs Konferenz 2	Poster Services, Security & Context Management Poster area	
15:30	Coffee break					
16:00 - 17:30	Panel Internet over Digital Video Broadcasting Networks Großer Saal					



Day 5: Thu, 23 June 2005

Time	Track 1	Track 2	Track 3	Track 4	Track 5	Track 6
09:00					Workshop W3: WIDENS: "The Future of Public Safety Wireless Communications"	Workshop W8: "How to Create a Successful Startup in Wireless"
12:30						
13:30	Workshop W7: WWI Projects: "Mobilising the European Contribution to the Wireless World"	Workshop W2: PULSERS Project: "Advances in the Development of UWB Systems for Europe"	Workshop W6: OBAN Project: "Mobility, QoS and Security in Open Wireless Access Networks"	Workshop W5: BROADBAND Forum and WIBRACE Forum: "Fixed-Wireless / Mobile-Satellite Convergence: Networks and Services"	Workshop W4: ACE-NEWCOM Networks of Excellence: "Smart Antennas, MIMO Systems and Channel Modelling"	Workshop W1: MAESTRO Project: "Mobile Broadcast: the Real Mobile Entertainment Killer Application?"
17:00						
-						
17:30						



The technical programme committee consists of individual experts as well as representatives of **all** FP6 projects.

Henrik Abramowicz (Sweden)	Peter Jung (Germany)
Hamid Aghvami (United Kingdom)	Stefan Kaiser (Germany)
Hans-Peter Bauer (Germany)	George T. Karetzos (Greece)
Sergio Benedetto (Italy)	Mika Klemettinen (Finland)
Friedbert Berens (Switzerland)	Ryuji Kohno (Japan)
Ezio Biglieri (Italy)	Sofoklis A. Kyriazakos (Greece)
János Bitó (Hungary)	Catherine Lamy (France)
Nicola Blefari-Melazzi (Italy)	Ralf Lehnert (Germany)
Holger Boche (Germany)	Khaled B. Letaief (Hong Kong)
Didier Bourse (France)	Juan Ramón López Caravantes (Spain)
Veselin Brankovic (Germany)	Petri Mähönen (Germany)
Fernando Casadevall Palacio (Spain)	Teresa H. Meng (USA)
Bruno Casali (Italy)	Heinrich Meyr (Germany)
Kwang-Cheng Chen (Taiwan)	Albena Mihovska (Denmark)
Zhi Ning Chen (Singapore)	Ingrid Moerman (Belgium)
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Klaus David (Germany)	Matthias Pätzold (Norway)
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Manuel Dinis (Portugal)	Ramjee Prasad (Denmark)
Christoph Dosch (Germany)	Emmanuel Protonotarios (Greece)
Catherine Douillard (France)	Christian Schäffer (Germany)
Einar Edvardsen (Norway)	Hans Schotten (Germany)
Heinz-Josef Eikerling (Germany)	Christophe Selier (France)
Hans-Joachim Einsiedler (Germany)	Rahim Tafazolli (United Kingdom)
Karim El-Khazen (France)	Sergios Theodoridis (Greece)
Adolf Finger (Germany)	Terje Tjelta (Norway)
István Frigyes (Hungary)	Rüdiger Urbanke (Switzerland)
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Laurent Hérault (France)	Markus Werner (Germany)
Walter Hirt (Switzerland)	Fiona Williams (Germany)
Axel Jahn (Germany)	Adam Wolisz (Germany)
Nigel Jefferies (United Kingdom)	

Organization

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